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[54] **SEMICONDUCTOR ELEMENT MODULE
AND SEMICONDUCTOR DEVICE WHICH
PREVENTS SHORT CIRCUITING**

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257/693, 698, 730

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[57] **ABSTRACT**

A semiconductor element module includes a package, a semiconductor element arranged on the package, and a plurality of leads provided on sides of the package so that an opening end of each the lead is oriented to the side of a package attaching plane, and serving to connect the semiconductor element to an external circuit; wherein a level difference is provided on the side of the package attaching plane of each of package sides so that a space is formed from each the plurality of leads.

10 Claims, 6 Drawing Sheets

